

WHAT IS CLAIMED IS:

1. A method of manufacturing a semiconductor device, comprising:
lowering a height of at least one of a plurality of external terminals that are electrically connected to a semiconductor chip mounted on one surface of a substrate and sealed with resin, and that are provided on another surface of the substrate in plural rows and plural columns.
2. The method of manufacturing a semiconductor device according to claim 1, further including grinding a tip of the at least one of the external terminals to lower the height.
3. The method of manufacturing a semiconductor device according to claim 1, further including lowering the height of the at least one of the external terminals such that tips of the plurality of external terminals are disposed in generally the same plane.
4. The method of manufacturing a semiconductor device according to claim 1, further including warping the substrate toward the side of a surface thereof on which the semiconductor chip is mounted.
5. The method of manufacturing a semiconductor device according to claim 1, further including warping the substrate toward the side of a surface thereof on which the external terminals are formed.
6. The method of manufacturing a semiconductor device according to claim 1, further including disposing the external terminals in an area array configuration.
7. The method of manufacturing a semiconductor device according to claim 1, further including, after forming the plurality of external terminals to the same height, lowering the height of at least one of the external terminals.
8. The method of manufacturing a semiconductor device according to claim 7, further including lowering the height of at least one of the external terminals to flatten tip surfaces thereof.
9. A semiconductor device, comprising:
a substrate, the substrate being warped;
a semiconductor chip mounted on one surface of the substrate and sealed with resin; and
a plurality of external terminals provided on another surface of the substrate in multiple rows and multiple columns, and electrically connected to the semiconductor chip, the plurality of the external terminals including tips that are disposed on generally the same plane.

10. The semiconductor device according to claim 9, the substrate being warped toward the side of a surface of the substrate on which the semiconductor chip is mounted.

11. The semiconductor device according to claim 9, the substrate being warped toward the side of a surface of the substrate on which the external terminals are mounted.

12. A semiconductor device, comprising:
a substrate;
a semiconductor chip mounted on one surface of the substrate and sealed with resin; and
a plurality of external terminals provided on another surface of the substrate in multiple rows and multiple columns, and electrically connected to the semiconductor chip, the plurality of external electrodes including tip surfaces that are flat and side surfaces that are curved.

13. A circuit substrate assembly, comprising:
a circuit substrate; and
the semiconductor device according to claim 9 mounted on the circuit substrate.

14. An electronic equipment, comprising:
the semiconductor device according to claim 9.